imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



3EZ6.2D5 Series

3 Watt DO-41 Surmetic™ 30 Zener Voltage Regulators

This is a complete series of 3 Watt Zener diodes with limits and excellent operating characteristics that reflect the superior capabilities of silicon-oxide passivated junctions. All this in an axial-lead, transfer-molded plastic package that offers protection in all common environmental conditions.

Specification Features:

- Zener Voltage Range 6.2 V to 18 V
- ESD Rating of Class 3 (>16 KV) per Human Body Model
- Surge Rating of 98 W @ 1 ms
- Maximum Limits Guaranteed on up to Six Electrical Parameters
- Package No Larger than the Conventional 1 Watt Package
- These are Pb-Free Devices*

Mechanical Characteristics:

CASE: Void free, transfer-molded, thermosetting plastic **FINISH:** All external surfaces are corrosion resistant and leads are readily solderable **MAXIMUM LEAD TEMPERATURE FOR SOLDERING PURPOSES:**

260°C, 1/16″ from the case for 10 seconds **POLARITY:** Cathode indicated by polarity band **MOUNTING POSITION:** Any

MAXIMUM RATINGS

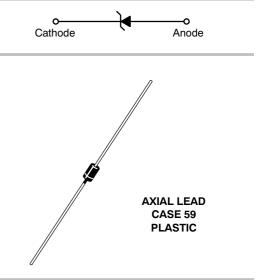
Rating	Symbol	Value	Unit
Max. Steady State Power Dissipation @ $T_1 = 75^{\circ}C$, Lead Length = $3/8''$	PD	3	W
Derate above 75°C		24	mW/°C
Steady State Power Dissipation @ $T_A = 50^{\circ}C$	PD	1	W
Derate above 50°C		6.67	mW/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-65 to +200	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

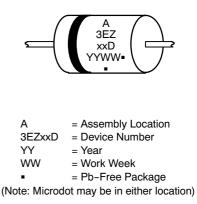


ON Semiconductor®

http://onsemi.com



MARKING DIAGRAM



ORDERING INFORMATION

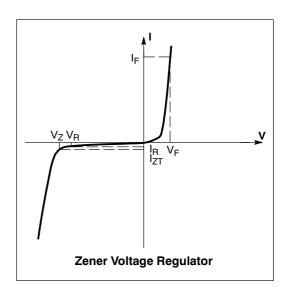
Device	Package	Shipping [†]
3EZxxD5G	Axial Lead (Pb-Free)	2000 Units / Box
3EZxxD5RLG	Axial Lead (Pb-Free)	6000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 1.5$ V Max @ $I_F = 200$ mA for all types)

Symbol	Parameter
VZ	Reverse Zener Voltage @ I _{ZT}
I _{ZT}	Reverse Current
Z _{ZT}	Maximum Zener Impedance @ I _{ZT}
I _{ZK}	Reverse Current
Z _{ZK}	Maximum Zener Impedance @ I _{ZK}
I _R	Reverse Leakage Current @ V _R
V _R	Breakdown Voltage
١ _F	Forward Current
V _F	Forward Voltage @ I _F
I _{ZM}	Maximum DC Zener Current
I _R	Surge Current @ T _A = 25°C



		Zener Voltage (Note 2)			Zener Impe	ner Impedance (Note 3)			Leakage Current		I _B	
Device†	Device	١	$V_{Z} \text{ (Volts)} \qquad @ I_{ZT} \qquad Z_{ZT} @ I_{ZT} \qquad Z_{ZK} @ I_{ZK}$		∂ I _{ZK}	I _R @ V _R		I _{ZM}	(Note 4)			
(Note 1)	Marking	Min	Nom	Max	mA	Ω	Ω	mA	μ Α Μax	Volts	mA	mA
3EZ6.2D5RLG	3EZ6.2D	5.89	6.2	6.51	121	1.5	700	1	5	3	435	3.1
3EZ13D5G	3EZ13D	12.35	13	13.65	58	4.5	700	0.25	0.5	9.9	208	1.54
3EZ16D5RLG	3EZ16D	15.2	16	16.8	47	5.5	700	0.25	0.5	12.2	169	1.25
3EZ18D5RLG	3EZ18D	17.1	18	18.9	42	6.0	750	0.25	0.5	13.7	150	1.11

1. TOLERANCE AND TYPE NUMBER DESIGNATION

Tolerance designation – device tolerance of $\pm 5\%$ are indicated by a "5" suffix.

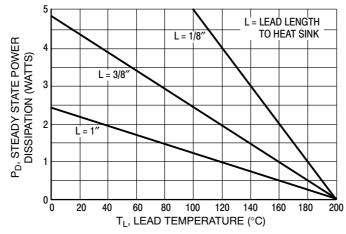
2. ZENER VOLTAGE (VZ) MEASUREMENT

ON Semiconductor guarantees the zener voltage when measured at 40 ms ±10 ms, 3/8" from the diode body. And an ambient temperature of 25°C (+8°C, -2°C)

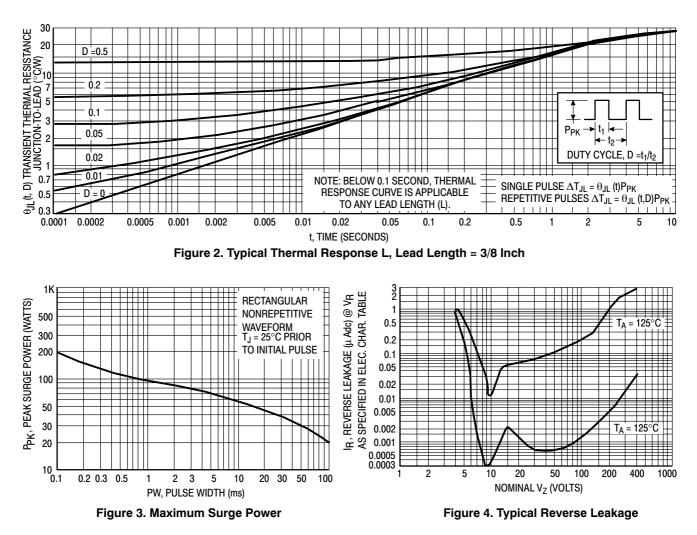
- ZENER IMPEDANCE (Z_Z) DERIVATION
 The zener impedance is derived from 60 seconds AC voltage, which results when an AC current having an rms value equal to 10% of the DC zener current (I_{ZT} or I_{ZK}) is superimposed on I_{ZT} or I_{ZK}.

 SURGE CURRENT (I_R) NON-REPETITIVE
- 4. SURGE CURRENT (I_R) NON-REPETITIVE The rating listed in the electrical characteristics table is maximum peak, non-repetitive, reverse surge current of 1/2 square wave or equivalent sine wave pulse of 1/120 second duration superimposed on the test current, I_{ZT}, per JEDEC standards. However, actual device capability is as described in Figure 3 of the General Data sheet for Surmetic 30s.

†The "G" suffix indicates these are Pb-Free packages.







APPLICATION NOTE

Since the actual voltage available from a given zener diode is temperature dependent, it is necessary to determine junction temperature under any set of operating conditions in order to calculate its value. The following procedure is recommended:

Lead Temperature, T_L, should be determined from:

$$\mathsf{T}_{\mathsf{L}} = \theta_{\mathsf{L}\mathsf{A}} \,\mathsf{P}_{\mathsf{D}} + \mathsf{T}_{\mathsf{A}}$$

 θ_{LA} is the lead-to-ambient thermal resistance (°C/W) and P_D is the power dissipation. The value for θ_{LA} will vary and depends on the device mounting method. θ_{LA} is generally 30–40°C/W for the various clips and tie points in common use and for printed circuit board wiring.

The temperature of the lead can also be measured using a thermocouple placed on the lead as close as possible to the tie point. The thermal mass connected to the tie point is normally large enough so that it will not significantly respond to heat surges generated in the diode as a result of pulsed operation once steady-state conditions are achieved. Using the measured value of T_L , the junction temperature may be determined by:

$$\mathsf{T}_{\mathsf{J}} = \mathsf{T}_{\mathsf{L}} + \Delta \mathsf{T}_{\mathsf{J}\mathsf{L}}$$

 ΔT_{JL} is the increase in junction temperature above the lead temperature and may be found from Figure 2 for a train of power pulses (L = 3/8 inch) or from Figure 10 for dc power.

$$T_{JL} = \theta_{JL} P_D$$

Λ

For worst-case design, using expected limits of I_Z , limits of P_D and the extremes of T_J (ΔT_J) may be estimated. Changes in voltage, V_Z , can then be found from:

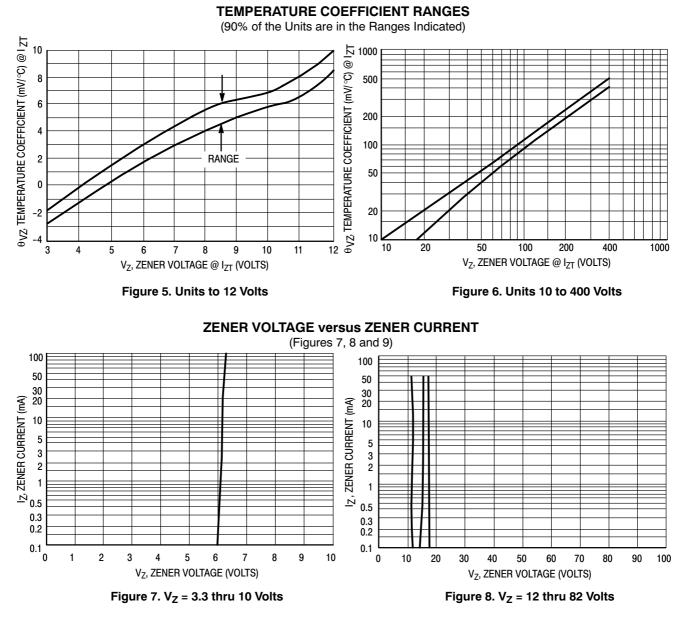
$$\Delta V = \theta_{VZ} \Delta T_J$$

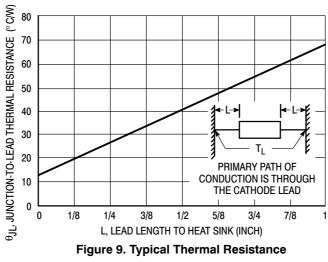
 θ_{VZ} , the zener voltage temperature coefficient, is found from Figures 5 and 6.

Under high power-pulse operation, the zener voltage will vary with time and may also be affected significantly by the zener resistance. For best regulation, keep current excursions as low as possible.

Data of Figure 2 should not be used to compute surge capability. Surge limitations are given in Figure 3. They are lower than would be expected by considering only junction temperature, as current crowding effects cause temperatures to be extremely high in small spots resulting in device degradation should the limits of Figure 3 be exceeded.

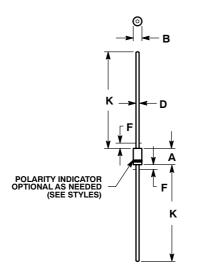
3EZ6.2D5 Series





PACKAGE DIMENSIONS

AXIAL LEAD CASE 59-01 ISSUE U



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2
- CONTROLLING DIMENSION: INCH. ALL RULES AND NOTES ASSOCIATED WITH З.
- JEDEC DO-41 OUTLINE SHALL APPLY POLARITY DENOTED BY CATHODE BAND.
- LEAD DIAMETER NOT CONTROLLED WITHIN F DIMENSION. 5

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.161	0.205	4.10	5.20		
В	0.079	0.106	2.00	2.70		
D	0.028	0.034	0.71	0.86		
F		0.050		1.27		
Κ	1.000		25.40			

Surmetic is a trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC observed on the provided in the evaluation of the rights of others. SCILLC products are not designed, intended, or authorized for use a components in systems intended for surgical implant into the body, or other applications and actual performance in the body, or other applications and actual performance in the body, or other applications are seen to the specifications are and context in the specifications are as components in systems intended for surgical implant into the body, or other applications are as components in systems intended for surgical implant into the body, or other applications are as components in systems intended for surgical implant into the body, or other applications are as components in systems intended for surgical implant into the body, or other applications are as components in systems intended for surgical implant into the body or other applications are as a components in systems intended for surgical implant into the body or other applications are applications and actual performance and actual perf intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, ad distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, and claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative